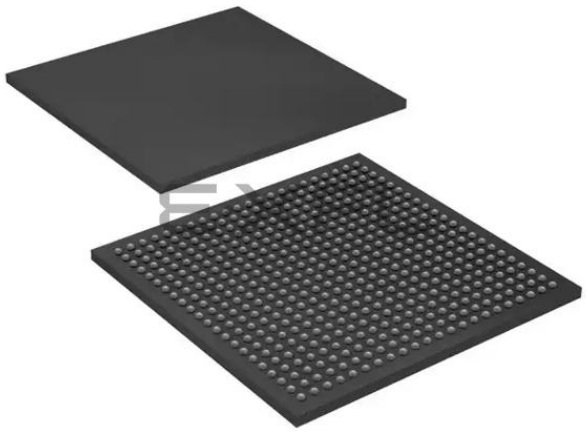

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	903
Number of Logic Elements/Cells	14448
Total RAM Bits	239616
Number of I/O	315
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c15af484i8n

Section III. Memory

Chapter 8. Cyclone II Memory Blocks

Chapter 9. External Memory Interfaces

Table 1–2. Cyclone II Package Options & Maximum User I/O Pins *Notes (1) (2)*

Device	144-Pin TQFP *(3)*	208-Pin PQFP *(4)*	240-Pin PQFP	256-Pin FineLine BGA	484-Pin FineLine BGA	484-Pin Ultra FineLine BGA	672-Pin FineLine BGA	896-Pin FineLine BGA
EP2C5 *(6) (8)*	89	142	—	158 *(5)*	—	—	—	—
EP2C8 *(6)*	85	138	—	182	—	—	—	—
EP2C8A *(6)*, *(7)*	—	—	—	182	—	—	—	—
EP2C15A *(6)*, *(7)*	—	—	—	152	315	—	—	—
EP2C20 *(6)*	—	—	142	152	315	—	—	—
EP2C20A *(6)*, *(7)*	—	—	—	152	315	—	—	—
EP2C35 *(6)*	—	—	—	—	322	322	475	—
EP2C50 *(6)*	—	—	—	—	294	294	450	—
EP2C70 *(6)*	—	—	—	—	—	—	422	622

Notes to Table 1–2:

(1) Cyclone II devices support vertical migration within the same package (for example, you can migrate between the EP2C20 device in the 484-pin FineLine BGA package and the EP2C35 and EP2C50 devices in the same package).

(2) The Quartus® II software I/O pin counts include four additional pins, `TDI`, `TDO`, `TMS`, and `TCK`, which are not available as general purpose I/O pins.

(3) TQFP: thin quad flat pack.

(4) PQFP: plastic quad flat pack.

(5) Vertical migration is supported between the EP2C5F256 and the EP2C8F256 devices. However, not all of the DQ and DQS groups are supported. Vertical migration between the EP2C5 and the EP2C15 in the F256 package is not supported.

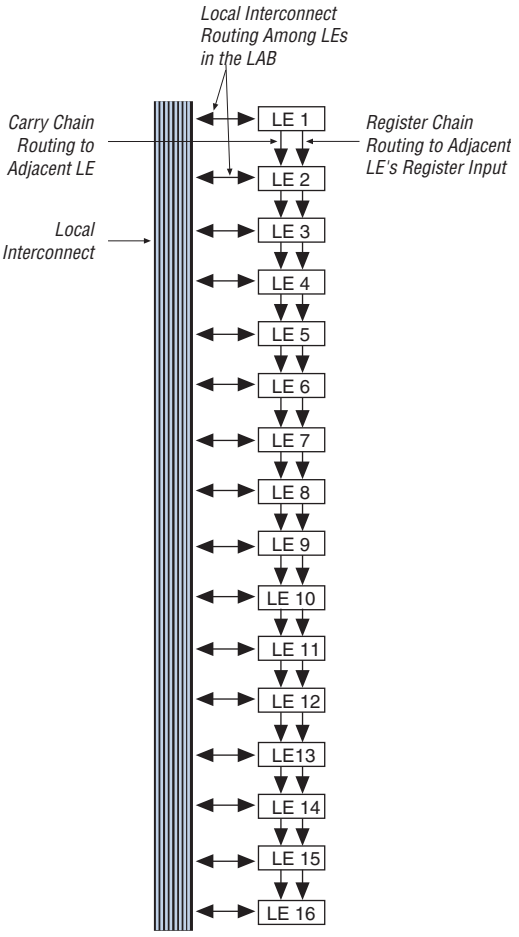
(6) The I/O pin counts for the EP2C5, EP2C8, and EP2C15A devices include 8 dedicated clock pins that can be used for data inputs. The I/O counts for the EP2C20, EP2C35, EP2C50, and EP2C70 devices include 16 dedicated clock pins that can be used for data inputs.

(7) EP2C8A, EP2C15A, and EP2C20A have a Fast On feature that has a faster POR time. The EP2C15A is only available with the Fast On option.

(8) The EP2C5 optionally support the Fast On feature, which is designated with an "A" in the device ordering code. The EP2C5A is only available in the automotive speed grade. Refer to the Cyclone II section in the *Automotive-Grade Device Handbook*.

Cyclone II devices support vertical migration within the same package (for example, you can migrate between the EP2C35, EPC50, and EP2C70 devices in the 672-pin FineLine BGA package). The exception to vertical migration support within the Cyclone II family is noted in Table 1–3.

Figure 2–9. Register Chain Interconnects



The C4 interconnects span four LABs, M4K blocks, or embedded multipliers up or down from a source LAB. Every LAB has its own set of C4 interconnects to drive either up or down. Figure 2–10 shows the C4 interconnect connections from an LAB in a column. The C4 interconnects can drive and be driven by all types of architecture blocks, including PLLs, M4K memory blocks, embedded multiplier blocks, and column and row IOEs. For LAB interconnection, a primary LAB or its LAB neighbor (see Figure 2–10) can drive a given C4 interconnect. C4 interconnects can drive each other to extend their range as well as drive row interconnects for column-to-column connections.

I/O Banks

The I/O pins on Cyclone II devices are grouped together into I/O banks and each bank has a separate power bus. EP2C5 and EP2C8 devices have four I/O banks (see Figure 2–28), while EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices have eight I/O banks (see Figure 2–29). Each device I/O pin is associated with one I/O bank. To accommodate voltage-referenced I/O standards, each Cyclone II I/O bank has a VREF bus. Each bank in EP2C5, EP2C8, EP2C15, EP2C20, EP2C35, and EP2C50 devices supports two VREF pins and each bank of EP2C70 supports four VREF pins. When using the VREF pins, each VREF pin must be properly connected to the appropriate voltage level. In the event these pins are not used as VREF pins, they may be used as regular I/O pins.

The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support all I/O standards listed in Table 2–17, except the PCI/PCI-X I/O standards. The left and right side I/O banks (banks 1 and 3 in EP2C5 and EP2C8 devices and banks 1, 2, 5, and 6 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support I/O standards listed in Table 2–17, except SSTL-18 class II, HSTL-18 class II, and HSTL-15 class II I/O standards. See Table 2–17 for a complete list of supported I/O standards.

The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support DDR2 memory up to 167 MHz/333 Mbps and QDR memory up to 167 MHz/668 Mbps. The left and right side I/O banks (1 and 3 of EP2C5 and EP2C8 devices and 1, 2, 5, and 6 of EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) only support SDR and DDR SDRAM interfaces. All the I/O banks of the Cyclone II devices support SDR memory up to 167 MHz/167 Mbps and DDR memory up to 167 MHz/333 Mbps.

DDR2 and QDRII interfaces may be implemented in Cyclone II side banks if the use of class I I/O standard is acceptable.

= 1000 / (1000/toggle rate at default load + derating factor * load value in pF/1000)

For example, the output toggle rate at 0 pF (default) load for SSTL-18 Class II 18mA I/O standard is 270 MHz on a –6 device column I/O pin. The derating factor is 29 ps/pF. For a 10pF load, the toggle rate is calculated as:

1000 / (1000/270 + 29 × 10/1000) = 250 (MHz)

Tables 5–44 through 5–46 show the I/O toggle rates for Cyclone II devices.

Table 5–44. Maximum Input Clock Toggle Rate on Cyclone II Devices (Part 1 of 2)

I/O Standard	Maximum Input Clock Toggle Rate on Cyclone II Devices (MHz)								
	Column I/O Pins			Row I/O Pins			Dedicated Clock Inputs		
	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
LVTTL	450	405	360	450	405	360	420	380	340
2.5V	450	405	360	450	405	360	450	405	360
1.8V	450	405	360	450	405	360	450	405	360
1.5V	300	270	240	300	270	240	300	270	240
LVCMOS	450	405	360	450	405	360	420	380	340
SSTL_2_CLASS_I	500	500	500	500	500	500	500	500	500
SSTL_2_CLASS_II	500	500	500	500	500	500	500	500	500
SSTL_18_CLASS_I	500	500	500	500	500	500	500	500	500
SSTL_18_CLASS_II	500	500	500	500	500	500	500	500	500
1.5V_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.5V_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
1.8V_HSTL_CLASS_I	500	500	500	500	500	500	500	500	500
1.8V_HSTL_CLASS_II	500	500	500	500	500	500	500	500	500
PCI	—	—	—	350	315	280	350	315	280
PCI-X	—	—	—	350	315	280	350	315	280
DIFFERENTIAL_SSTL_2_CLASS_I	500	500	500	500	500	500	500	500	500
DIFFERENTIAL_SSTL_2_CLASS_II	500	500	500	500	500	500	500	500	500

Each output port has a unique post-scale counter to divide down the high-frequency VCO. There are three post-scale counters (c0, c1, and c2), which range from 1 to 32. The following equations show the frequencies for the three post-scale counters:

$$f_{C0} = \frac{f_{VCO}}{C0} = f_{IN} \frac{m}{n \times C0}$$

$$f_{C1} = \frac{f_{VCO}}{C1} = f_{IN} \frac{m}{n \times C1}$$

$$f_{C2} = \frac{f_{VCO}}{C2} = f_{IN} \frac{m}{n \times C2}$$

All three output counters can drive the global clock network. The c2 output counter can also drive a dedicated external I/O pin (single ended or differential). This counter output can drive a dedicated external clock output pin (`PLL<#>_OUT`) and the global clock network at the same time.

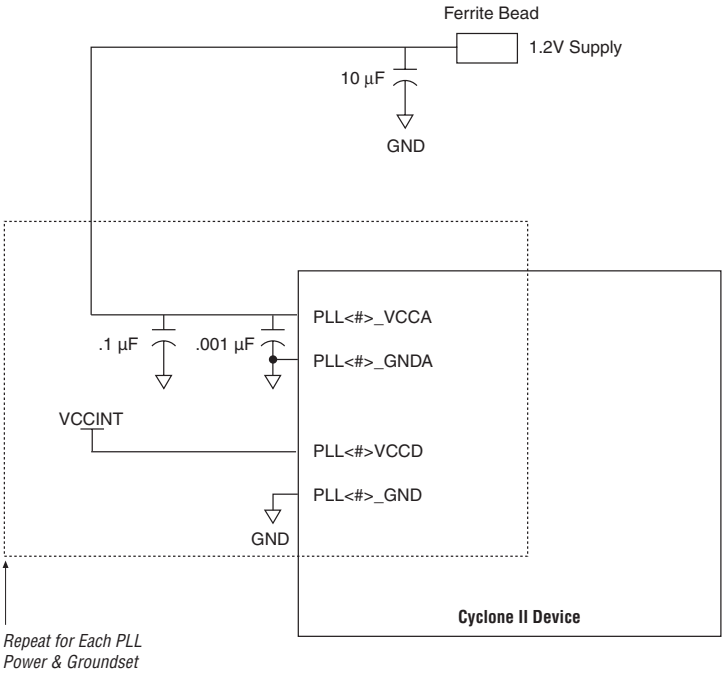
For multiple PLL outputs with different frequencies, the VCO is set to the least common multiple of the output frequencies that meets the VCO frequency specifications. Then, the post-scale counters scale down the VCO frequency for each PLL clock output port. For example, if clock output frequencies required from one PLL are 33 and 66 MHz, the VCO is set to 330 MHz (the least common multiple in the VCO's range).

Programmable Duty Cycle

The programmable duty cycle feature allows you to set the PLL clock output duty cycles. The duty cycle is the ratio of the clock output high and low time to the total clock cycle time, expressed as a percentage of high time. This feature is supported on all three PLL post-scale counters, c0, c1, and c2, and when using all clock feedback modes.

The duty cycle is set by using a low- and high-time count setting for the post-scale counters. The Quartus II software uses the input frequency and target multiply/divide ratio to select the post-scale counter. The granularity of the duty cycle is determined by the post-scale counter value chosen on a PLL clock output and is defined as 50% ÷ post-scale counter value. For example, if the post-scale counter value is 3, then the allowable duty cycle precision would be 50% ÷ 3 = 16.67%. Because the `altpll` megafunction does not accept non-integer values for the duty cycle values, the allowable duty cycles are 17% 33% 50% and 67%. For example, if the c0 counter is 10, then steps of 5% are possible for duty cycle choices between 5 to 90%.

Figure 7–17. PLL Power Schematic for Cyclone II PLLs



Note to Figure 7–17:
(1) Applies to PLLs 1 through 4.

VCCD & GND

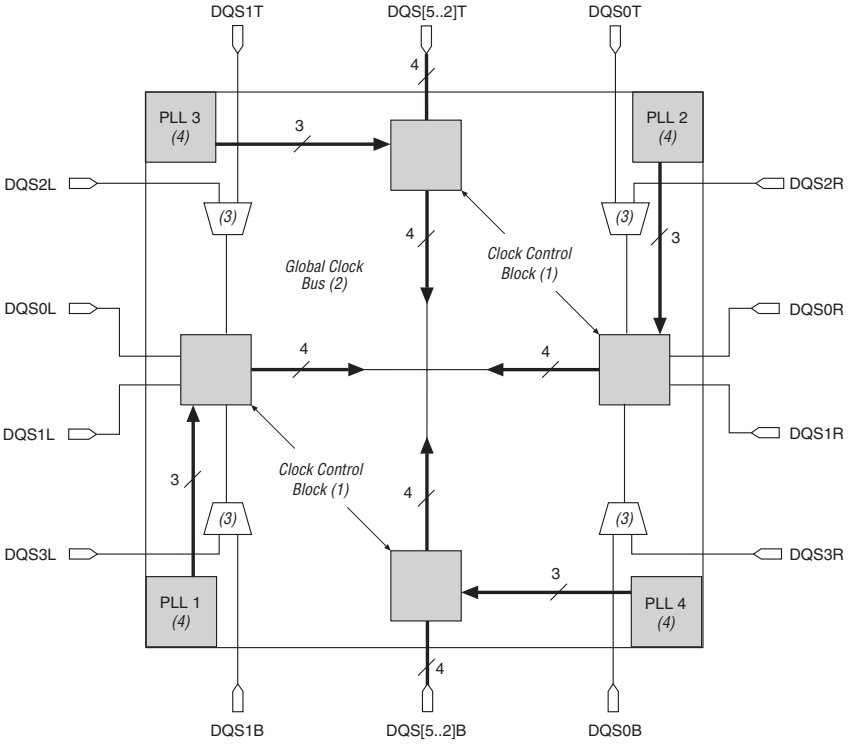
The digital power and ground pins are labeled VCCD_ PLL<*PLL number*> and GND_PLL<*PLL number*>. The VCCD pin supplies the power for the digital circuitry in the PLL. Connect these VCCD pins to the quietest digital supply on the board. In most systems, this is the digital 1.2-V supply supplied to the device's V_{CCINT} pins. Connect the VCCD pins to a power supply even if you do not use the PLL. When connecting the V_{CCD} pins to V_{CCINT}, you do not need any filtering or isolation. You can connect the GND pins directly to the same ground plane as the device's digital ground. See Figure 7–17.

Conclusion

Cyclone II device PLLs provide you with complete control of device clocks and system timing. These PLLs support clock multiplication/division, phase shift, and programmable duty cycle for your cost-sensitive clock synthesis applications.

directly to the clock control block. For the larger Cyclone II devices, the corner DQS signals are multiplexed before they are routed to the clock control block. When you use the corner DQS pins for DDR implementation, there is a degradation in the performance of the memory interface. The clock control block is used to select from a number of input clock sources, in this case either PLL clock outputs or DQS pins, to drive onto the global clock bus. Figure 9–7 shows the corner DQS signal mappings for EP2C15 through EP2C70 devices.

Figure 9–7. Corner DQS Signal Mapping for EP2C15–EP2C70 Devices



Notes to Figure 9–7:

(1) There are four control blocks on each side.
(2) There are a total of 16 global clocks available.
(3) Only one of the corner DQS pins in each corner can feed the clock control block at a time. The other DQS pins can be used as general purpose I/O pins.
(4) PLL resource can be lost if all DQS pins from one side are used at the same time.
(5) Top/bottom and side IOE have different timing.

Section IV. I/O Standards

This section provides information on Cyclone® II single-ended, voltage referenced, and differential I/O standards.

This section includes the following chapters:

- Chapter 10, Selectable I/O Standards in Cyclone II Devices
- Chapter 11, High-Speed Differential Interfaces in Cyclone II Devices

Revision History

Refer to each chapter for its own specific revision history. For information on when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

For information about the I/O standards supported for external memory applications, refer to the *External Memory Interfaces* chapter in volume 1 of the *Cyclone II Device Handbook*.

Table 10–1. Cyclone II Supported I/O Standards and Constraints (Part 1 of 2)

I/O Standard	Type	V_{CCIO} Level		Top and Bottom I/O Pins		Side I/O Pins		
		Input	Output	CLK, DQS	User I/O Pins	CLK, DQS	PLL_OUT	User I/O Pins
3.3-V LVTTL and LVCMOS	Single ended	3.3 V/ 2.5 V	3.3 V	✓	✓	✓	✓	✓
2.5-V LVTTL and LVCMOS	Single ended	3.3 V/ 2.5 V	2.5 V	✓	✓	✓	✓	✓
1.8-V LVTTL and LVCMOS	Single ended	1.8 V/ 1.5 V	1.8 V	✓	✓	✓	✓	✓
1.5-V LVCMOS	Single ended	1.8 V/ 1.5 V	1.5 V	✓	✓	✓	✓	✓
SSTL-2 class I	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-2 class II	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
SSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	*(1)*	*(1)*	*(1)*
HSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
HSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	*(1)*	*(1)*	*(1)*
HSTL-15 class I	Voltage referenced	1.5 V	1.5 V	✓	✓	✓	✓	✓
HSTL-15 class II	Voltage referenced	1.5 V	1.5 V	✓	✓	*(1)*	*(1)*	*(1)*
PCI and PCI-X *(2)*	Single ended	3.3 V	3.3 V	—	—	✓	✓	✓
Differential SSTL-2 class I or class II	Pseudo differential *(3)*	*(4)*	2.5 V	—	—	—	✓	—
		2.5 V	*(4)*	✓ *(5)*	—	✓ *(5)*	—	—
Differential SSTL-18 class I or class II	Pseudo differential *(3)*	*(4)*	1.8 V	—	—		✓ *(6)*	—
		1.8 V	*(4)*	✓ *(5)*	—	✓ *(5)*	—	—

Table 10–5 shows I/O standards supported when a pin is used as a regular I/O pin in the I/O banks of Cyclone II devices.

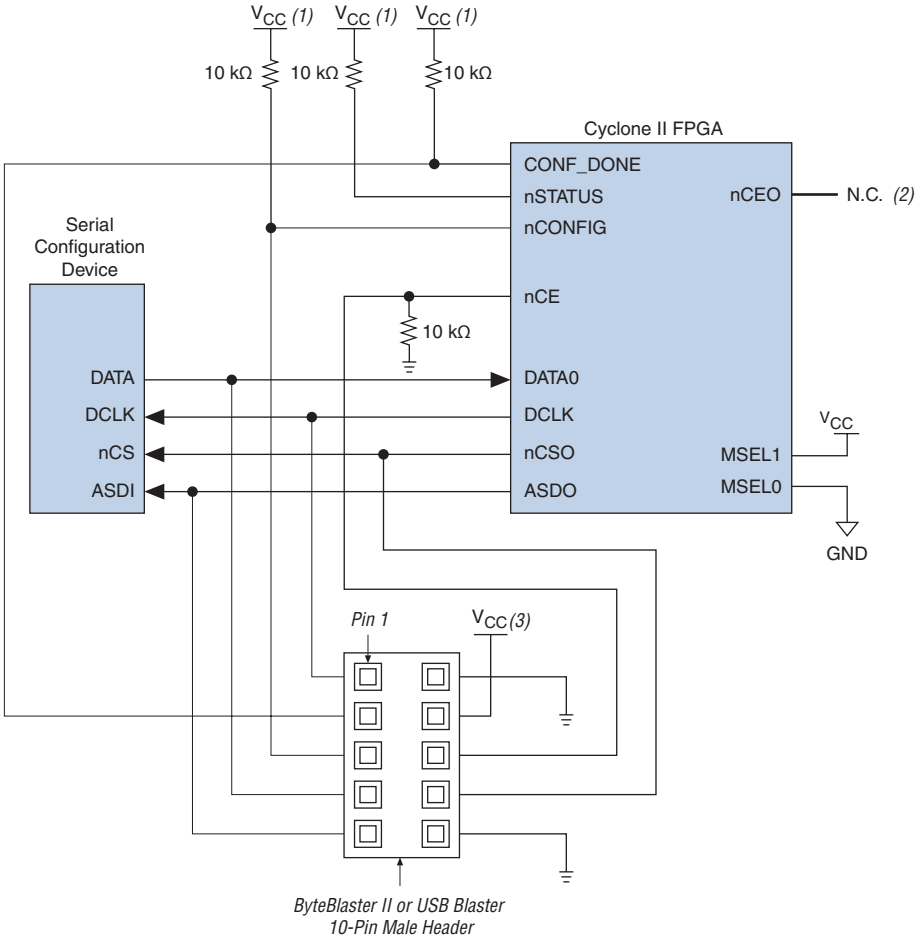
Programmable Current Drive Strength

The Cyclone II device I/O standards support various output current drive settings as shown in Table 10–6. These programmable drive-strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for I_{OH} and I_{OL} of the corresponding I/O standard.

Table 10–6. Programmable Drive Strength (Part 1 of 2)

I/O Standard	I_{OH}/I_{OL} Current Strength Setting (mA)	
	Top and Bottom I/O Pins	Side I/O Pins
LVTTL (3.3 V)	4	4
	8	8
	12	12
	16	16
	20	20
	24	24
LVCMOS (3.3 V)	4	4
	8	8
	12	12
	16	—
	20	—
	24	—
LVTTL and LVCMOS (2.5 V)	4	4
	8	8
	12	—
	16	—
LVTTL and LVCMOS (1.8 V)	2	2
	4	4
	6	6
	8	8
	10	10
	12	12
LVCMOS (1.5 V)	2	2
	4	4
	6	6
	8	—

Figure 13–7. In-System Programming of Serial Configuration Devices



Notes to Figure 13–7:

(1) Connect these pull-up resistors to 3.3-V supply.

(2) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed other device's nCE pin.

(3) Power up the ByteBlaster II or USB Blaster cable's V_{CC} with a 3.3-V supply.

You can use the Quartus II software with the APU and the appropriate configuration device programming adapter to program serial configuration devices. All serial configuration devices are offered in an 8-pin or 16-pin small outline integrated circuit (SOIC) package and can be programmed using the PLMSEPC-8 adapter.

PS Configuration

You can use an Altera configuration device, a download cable, or an intelligent host, such as a MAX® II device or microprocessor to configure a Cyclone II device with the PS scheme. In the PS scheme, an external host (configuration device, MAX II device, embedded processor, or host PC) controls configuration. Configuration data is input to the target Cyclone II devices via the DATA0 pin at each rising edge of DCLK.

The Cyclone II decompression feature is fully available when configuring your Cyclone II device using PS mode.

Table 13–6 shows the MSEL pin settings when using the PS configuration scheme.

Table 13–6. Cyclone II MSEL Pin Settings for PS Configuration Schemes

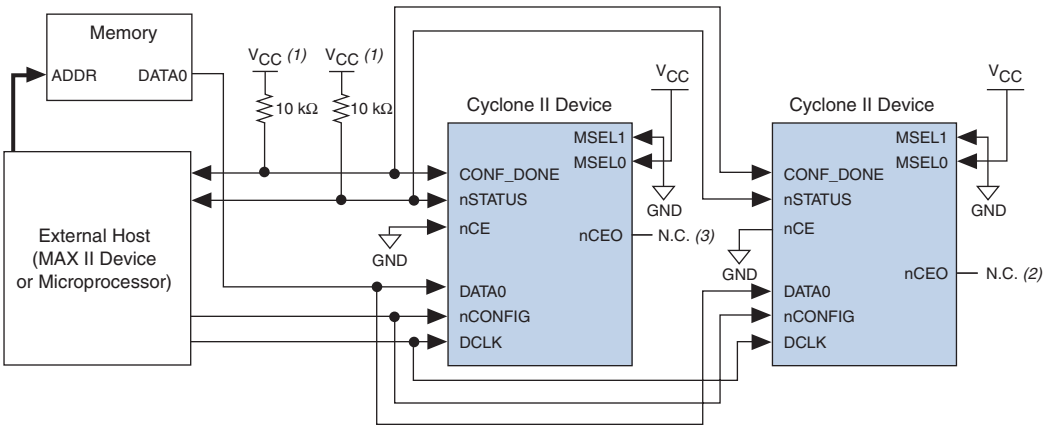
Configuration Scheme	MSEL1	MSEL0
PS	0	1

Single Device PS Configuration Using a MAX II Device as an External Host

In the PS configuration scheme, you can use a MAX II device as an intelligent host that controls the transfer of configuration data from a storage device, such as flash memory, to the target Cyclone II device. Configuration data can be stored in RBF, HEX, or TTF format. Figure 13–9 shows the configuration interface connections between the Cyclone II device and a MAX II device for single device configuration.

If your system has multiple Cyclone II devices (in the same density and package) with the same configuration data, you can configure them in one configuration cycle by connecting all device's nCE pins to ground and connecting all the Cyclone II device's configuration pins (nCONFIG, nSTATUS, DCLK, DATA0, and CONF_DONE) together. You can also use the nCEO pin as a user I/O pin after configuration. The configuration signals may require buffering to ensure signal integrity and prevent clock skew problems. Make sure the DCLK and DATA lines are buffered for every fourth device. All devices start and complete configuration at the same time. Figure 13–11 shows multiple device PS configuration when both Cyclone II devices are receiving the same configuration data.

Figure 13–11. Multiple Device PS Configuration When Both FPGAs Receive the Same Data



Notes to Figure 13–11:

(1) The pull-up resistor should be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} should be high enough to meet the V_{IH} specification of the I/O on the devices and the external host.

(2) The nCEO pins of both devices can be left unconnected or used as user I/O pins when configuring the same configuration data into multiple devices.

You can use a single configuration chain to configure Cyclone II devices with other Altera devices. Connect all the Cyclone II device's and all other Altera device's CONF_DONE and nSTATUS pins together so all devices in the chain complete configuration at the same time or that an error reported by one device initiates reconfiguration in all devices.

For more information on configuring multiple Altera devices in the same configuration chain, see *Configuring Mixed Altera FPGA Chains* in the *Configuration Handbook*.

enables the programming software to program or verify the target device. Configuration data driven into the target device appears on the TDO pin one clock cycle later.

The Quartus II software verifies successful JTAG configuration upon completion. At the end of configuration, the software checks the CONF_DONE pin through the JTAG port. When the Quartus II software generates a JAM file for a multiple device chain, it contains instructions so that all the devices in the chain are initialized at the same time. If CONF_DONE is not high, the Quartus II software indicates that configuration has failed. If the CONF_DONE pin transitions high, the software indicates that configuration was successful. After the configuration bitstream is transmitted serially via the JTAG TDI port, the TCK port is clocked an additional 299 cycles to perform Cyclone II device initialization.

The **Enable user-supplied start-up clock (CLKUSR)** option has no affect on the device initialization since this option is disabled in the SOF when configuring the FPGA in JTAG using the Quartus II programmer and download cable. Therefore, if you turn on the CLKUSR option, you do not need to provide a clock on CLKUSR when you are configuring the FPGA with the Quartus II programmer and a download cable.

Cyclone II devices have dedicated JTAG pins that always function as JTAG pins. You can perform JTAG testing on Cyclone II devices before, after, and during configuration. Cyclone II devices support the BYPASS, IDCODE and SAMPLE instructions during configuration without interruption. All other JTAG instructions may only be issued by first interrupting configuration and reprogramming I/O pins using the CONFIG_IO instruction.

The CONFIG_IO instruction allows I/O buffers to be configured via the JTAG port. The CONFIG_IO instruction interrupts configuration. This instruction allows you to perform board-level testing before configuring the Cyclone II device or waiting for a configuration device to complete configuration. If you interrupt configuration, the Cyclone II device must be reconfigured via JTAG (PULSE_CONFIG instruction) or by pulsing nCONFIG low after JTAG testing is complete.

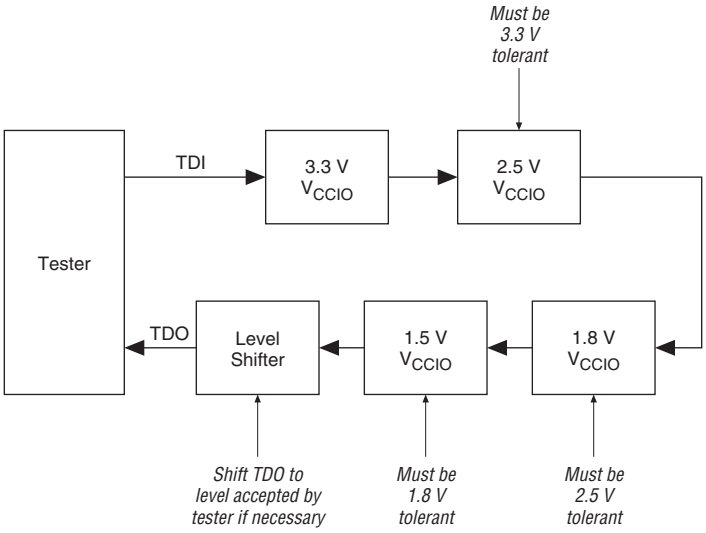
For more information, see the *MorphIO: An I/O Reconfiguration Solution for Altera White Paper*.

The chip-wide reset (DEV_CLRn) and chip-wide output enable (DEV_OE) pins on Cyclone II devices do not affect JTAG boundary-scan or programming operations. Toggling these pins does not affect JTAG operations (other than the usual boundary-scan operation).

Table 13–11. Dedicated Configuration Pins on the Cyclone II Device (Part 4 of 5)

Pin Name	User Mode	Configuration Scheme	Pin Type	Description
nCEO	N/A if option is on. I/O if option is off.	All	Output	This pin is an output that drives low when device configuration is complete. In single device configuration, you can leave this pin floating or use it as a user I/O pin after configuration. In multiple device configuration, this pin inputs the next device's nCE pin. The nCEO of the last device in the chain can be left floating or used as a user I/O pin after configuration. If you use the nCEO pin to feed next device's nCE pin, use an external 10-kΩ pull-up resistor to pull the nCEO pin high to the V_{CCIO} voltage of its I/O bank to help the internal weak pull-up resistor. Use the Quartus II software to make this pin a user I/O pin.
ASDO	N/A in AS mode I/O in PS and JTAG mode	AS	Output	This pin sends a control signal from the Cyclone II device to the serial configuration device in AS mode and is used to read out configuration data. In AS mode, ASDO has an internal pull-up that is always active.
nCSO	N/A in AS mode I/O in PS and JTAG mode	AS	Output	This pin sends an output control signal from the Cyclone II device to the serial configuration device in AS mode that enables the configuration device. In AS mode, nCSO has an internal pull-up resistor that is always active.

Figure 14–13. JTAG Chain of Mixed Voltages



Using IEEE Std. 1149.1 BST Circuitry

Cyclone II devices have dedicated JTAG pins, and the IEEE Std. 1149.1 BST circuitry is enabled upon device power-up. You can perform BST on Cyclone II FPGAs not only before and after configuration, but also during configuration. Cyclone II FPGAs support the BYPASS, IDCODE, and SAMPLE instructions during configuration without interrupting configuration. To send all other JTAG instructions, you must interrupt configuration using the CONFIG_IO instruction.

The CONFIG_IO instruction allows you to configure I/O buffers via the JTAG port, and when issued, interrupts configuration. This instruction allows you to perform board-level testing prior to configuring the Cyclone II FPGA or waiting for a configuration device to complete configuration. Once configuration has been interrupted and JTAG BST is complete, the part must be reconfigured via JTAG (PULSE_CONFIG instruction) or by pulsing nCONFIG low.

When you perform JTAG boundary-scan testing before configuration, the nCONFIG pin must be held low.

The device-wide reset (DEV_CLRn) and device-wide output enable (DEV_OE) pins on Cyclone II devices do not affect JTAG boundary-scan or configuration operations. Toggling these pins does not disrupt BST operation any more than usual.

Figure 15–7 shows a 672-pin FineLine BGA package outline.

Figure 15–7. 672-Pin FineLine BGA Package Outline